What is claimed is:

1. A method of wetting a semiconductor wafer with slurry, said method comprising: using a wear ring to hold the wafer to a polishing pad, said wear ring including at least one channel and a plurality of outlets in communication with the at least one channel; injecting the slurry into the at least one channel such that the slurry exits the outlets in the wear ring and contacts the polishing pad.

2. A method as recited in claim 1, further comprising pressing the wear ring against the polishing pad.

3. A method as recited in claim 1, wherein the polishing pad is disposed on a polishing table and said method further comprises rotating at least one of the wear ring and the polishing table.

4. A method as recited in claim 1, wherein the polishing pad is disposed on a polishing table and said method further comprises rotating both the wear ring and the polishing table.

5. A method as recited in claim 1, wherein the wear ring includes at least one inlet in communication with the at least one channel, said step of injecting the slurry into the at least one channel comprises injecting the slurry into the at least one inlet.

6. A wear ring which is configured to hold a semiconductor wafer and is configured to be disposed on a polishing pad, said wear ring including at least one channel and a plurality of outlets in communication with the at least one channel, said wear ring configured such that slurry is injectable into the at least one channel such that the slurry exits the outlets in the wear ring and contacts the polishing pad.

7. A wear ring as recited in claim 6, wherein said wear ring is pressable against the polishing pad.

8. A wear ring as recited in claim 6, wherein the wear ring includes at least one inlet in communication with the at least one channel.